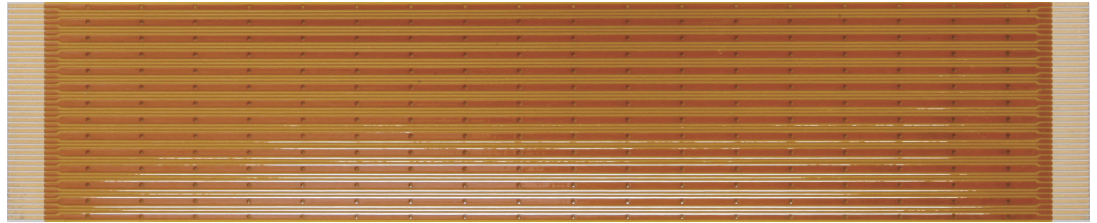
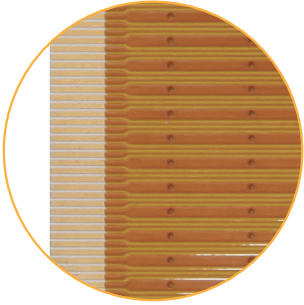


YFC LVDS Type

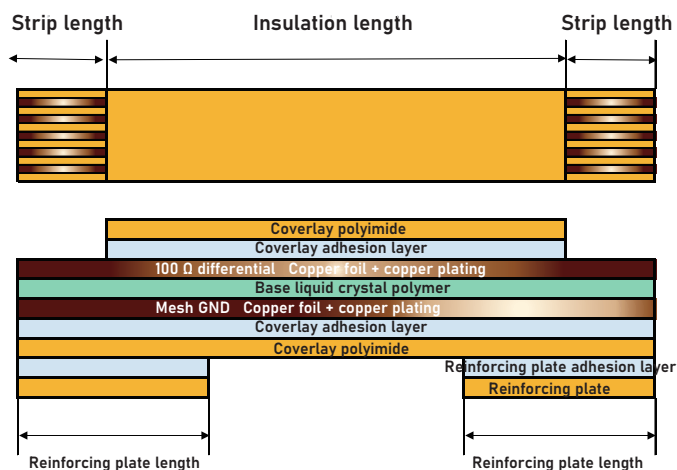
Microstripline



Features

- A transmission loss is reduced by using a liquid crystal polymer for a base.
- A type in which polyimide is used for coverlay can be also used for hand soldering.
- Flexibility is improved in performance by use of mesh GND.

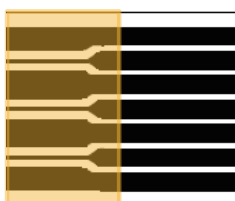
Configuration example



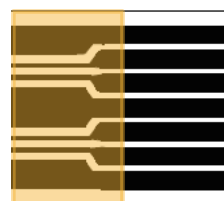
Standard specifications

Base materials	: Liquid crystal polymer
Cover materials	: Polyimide/liquid crystal polymer
Terminal pitch	: 0.5 mm
Terminal area thickness	: 0.3 mm ± 0.05 mm
Number of compatible cores	: G/S/G type 2n + 1 (3, 5, 7, 9, 11.....) G/S/S/G type 3n + 1 (4, 7, 10, 13, 16.....)
Impedance:	: 50 Ω single-ended (±10%) 100 Ω differential (±10%)

Conceptual diagram of terminal area



Black: Wiring
G/S/G type
RFM1 (Polyimide cover)
RFM3 (Liquid crystal polymer cover)



Black: Wiring
G/S/S/G type
RFM2 (Polyimide cover)
RFM4 (Liquid crystal polymer cover)